BGA PACKAGE VACUUM PAD

ABSTRACT

Disclosed herein is a vacuum pad for adsorptively fixing or transferring a BGA (Ball Grid Array) package. The BGA package vacuum pad includes a vacuum hole communicating with a vacuum line and a contact part protruding from the edge of the upper surface thereof. The contact part has recesses formed thereon for accommodating balls of a BGA package.

Figure no. 2a is suggested for the purpose of publication.